| L Number | Hits | Search Text | DB | Time stamp |
|---|---|---|---|---|
| -- | 427 | (432/253).CCLS. | USPAT | 2004/01/08 14:56 |
| -- | 169 | (wafer or substrate) and ((432/253).CCLS.) | USPAT | 2004/01/08 15:14 |
| -- | 223 | (432/258).CCLS. | USPAT | 2004/01/08 15:14 |
| -- | 74 | (wafer or substrate) and ((432/258).CCLS.) | USPAT | 2004/01/08 15:25 |
| -- | 34 | ((wafer or substrate) and ((432/258).CCLS.)) not ((wafer or substrate) and ((432/253).CCLS.)) | USPAT | 2004/01/08 15:24 |
| -- | 776 | ((392/416) or (392/418)).CCLS. | USPAT | 2004/01/08 15:25 |
| -- | 411 | (wafer or substrate) and (((392/416) or (392/418)).CCLS.) | USPAT | 2004/01/08 16:16 |
| -- | 394 | ((wafer or substrate) and (((392/416) or (392/418)).CCLS.)) not ((((wafer or substrate) and ((432/258).CCLS.)) not ((wafer or substrate) and ((432/253).CCLS.))) or ((wafer or substrate) and ((432/253).CCLS.))) | USPAT | 2004/01/08 16:15 |
| -- | 314 | (432/247).CCLS. | USPAT | 2004/01/08 16:17 |
| -- | 20 | (wafer or substrate) and ((432/247).CCLS.) | USPAT | 2004/01/08 16:17 |
| -- | 102 | (432/237).CCLS. | USPAT | 2004/01/08 16:17 |
| -- | 3 | (wafer or substrate) and ((432/237).CCLS.) | USPAT | 2004/01/08 16:18 |
| -- | 388 | (432/250).CCLS. | USPAT | 2004/01/08 16:18 |
| -- | 23 | (wafer or substrate) and ((432/250).CCLS.) | USPAT | 2004/01/08 16:21 |
| -- | 75 | (219/443.1).CCLS. | USPAT | 2004/01/08 16:22 |
| -- | 10 | (wafer or substrate) and ((219/443.1).CCLS.) | USPAT | 2004/01/08 16:22 |
| -- | 120 | (219/444.1).CCLS. | USPAT | 2004/01/08 16:22 |
| -- | 112 | (wafer or substrate) and ((219/444.1).CCLS.) | USPAT | 2004/01/08 16:32 |
| -- | 952 | (heat$3 NEAR4 platen) and (wafer or substrate) and upper and lower | USPAT | 2004/01/08 16:33 |
| -- | 267 | semiconductor and ((heat$3 NEAR4 platen) and (wafer or substrate) and upper and lower ) | USPAT | 2004/01/08 16:34 |
| -- | 38 | lid and (semiconductor and ((heat$3 NEAR4 platen) and (wafer or substrate) and upper and lower )) | USPAT | 2004/01/09 07:22 |
| -- | 2285 | (lid or cover).ab. and (wafer or semiconductor) and thermal | USPAT | 2004/01/09 07:23 |
| -- | 362 | lid.ab. and (wafer or semiconductor) and thermal | USPAT | 2004/01/09 07:23 |

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